



Final Product Change Notification

202309003F07 : Introduction of Multi-Source Optical Shrink Versions of Leadless HVSON-package Product TJA1057

Note: This notice is NXP Company Proprietary.

Issue Date: Feb 10, 2025 **Effective Date:** May 11, 2025

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Management summary

NXP Product Line In-Vehicle Networking (PL IVN) will be introducing multi-source optical shrink versions of leadless HVSON-package product TJA1057

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input checked="" type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input checked="" type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware <input checked="" type="checkbox"/> Other: Optical shrink				

Notification Overview

Description

For the PL IVN leadless HVSON-package CAN product TJA1057 optical shrink Quad Source product versions will be introduced. The Bill-of-Material (BoM) of those new shrink product versions will be using copper (Cu) bondwire, with the associated mold compound and die attach. The new product versions are introduced as Quad Source, i.e. using two front-end diffusion waferfabs and two back-end assembly and final test sites.

This change does not affect the currently released NXP 12NC product part numbers for leadless HVSON-package TJA1057. New 12NCs have been created to make use of the optical shrink Quad Source.

In the attachment to this Product Change Notification (PCN) details of the changes involved are given, as well as three additional documents:

- The AEC-Q100 qualification results for the release
- The applicable ZVEI Delta Qualification Matrix (DeQuMa), both in zipped excel and pdf format

See the paragraphs 'Additional information' and 'Remarks' below for instructions on how to obtain these documents. Attached to this e-mail is an excel file with two sheets. One contains the sales history for your affected part numbers, the other the product change list. In both sheets reference is made to new part number, orderable part number and NXP 12NC code. In case you want to make use of the optical shrink Quad Source you need to order this new part number.

Reason

These changes will help to continue NXP's Global Business Continuity Management process to establish an industrial base that is agile, robust and can reliably service the long term forecasted market growth of IVN products.

Identification of Affected Products

Top Side Marking

In the attachment to this PCN it is shown how the product name and the marking changes.

Product Availability

Sample Information

Samples are available upon request

Production

Planned first shipment May 10, 2025

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on specification, form, fit, function(ality), performance, reliability or quality

Data Sheet Revision

No impact to existing data sheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Self qualification:[view online](#)

Additional documents: [view online](#)

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Mar 12, 2025.

Remarks

As direct recipient of this NXP PL IVN PCN, please use the 'view online' under the heading 'Additional information' above, to log in to the NXP e-PCN system you're subscribed to, in order to obtain the attached documents with relevant detailed information from the tab 'Files'. If you're not the original recipient, i.e. this PCN has been forwarded to you, you should contact the original recipient(s) within your company or your distribution supplier to obtain the attachments.

A PPAP for the changed product is available on request, and can only be obtained by your (local) NXP sales contact(s) for you. Also samples can be requested via your (local) NXP sales contact(s).

Should you, after having read both PCN and its attachment with detailed explanation, still have questions, please contact us via below a-mail address.

Related Notification

Notification	Issue Date	Effective Date	Title
202302010I	Feb 17, 2023	Mar 17, 2023	TJA1057 Datasheet Update
202309003A	Nov 02, 2023		Introduction of Multi-Source Optical Shrink Versions of Various CAN/LIN Products
202309003F05	Feb 21, 2024	May 21, 2024	Introduction of Multi-Source Optical Shrink Versions of SO-Package Product TJA1057
202411011I	Nov 22, 2024	Dec 23, 2024	Datasheet Update for TJA1044(V) and TJA1057 Products

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Quality Account Manager

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NXP Quality Management Team.

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